



Material Content Data Sheet



Sales Product Name		IFX1050G VIO		Issued		24. January 2018			
MA#		MA001631392							
Package		PG-DSO-8-16		Weight*		83.56 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.700	4.43	4.43	44280	44280	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107		
		non noble metal	zinc	7440-66-6	0.036	0.04		429	
		non noble metal	iron	7439-89-6	0.717	0.86		8583	
wire	noble metal	non noble metal	copper	7440-50-8	29.121	34.85	35.76	348500	357619
		noble metal	gold	7440-57-5	0.118	0.14	0.14	1413	1413
		organic material	carbon black	1333-86-4	0.094	0.11		1120	
encapsulation	plastics	epoxy resin	-	4.305	5.15		51525		
		inorganic material	silicondioxide	60676-86-0	42.400	50.74	56.00	507408	560053
leadfinish	non noble metal	tin	7440-31-5	0.824	0.99	0.99	9861	9861	
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7782	7782	
glue	plastics	acrylic resin	-	0.349	0.42		4178		
		noble metal	silver	7440-22-4	1.238	1.48	1.90	14814	18992
*deviation	< 10%				Sum in total:		100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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